



TSMC 2024 Supply Chain Management Forum Presents Awards to Outstanding Suppliers

HSINCHU, Taiwan, R.O.C, Dec. 2, 2024 - TSMC (TWSE: 2330, NYSE: TSM) today held its 2024 Supply Chain Management Forum and presented awards to outstanding supplier partners in gratitude for their remarkable contributions over the past year. These contributions have strengthened TSMC's technology leadership and expanded its global manufacturing footprint, jointly achieving excellence and unleashing innovation for customers worldwide.

The forum, themed "Empowering the Future with a Sustainable Semiconductor Ecosystem," featured keynote speakers, Paul Polman, an internationally celebrated leader in global sustainability and climate and equality advocacy, and John Langan, CTO of Merck Group and an expert on how to use AI and data analysis to improve processes and achieve carbon reduction. They shared insights on blending sustainability with business strategies and revolutionary green technology. The event also included breakout sessions covering topics such as advanced packaging, materials, and gender empowerment, encouraging innovation and dialogue to enhance supply chain resilience and growth momentum.

"The semiconductor ecosystem and global supply chain are not only essential to TSMC's success but also play a pivotal role in shaping future technology," said TSMC Chairman & CEO Dr. C.C. Wei. "It is imperative to continually enhance strategic planning, build robust capacity, reinforce resilience, and elevate quality performance. Additionally, we must ensure our initiatives positively impact both sustainability and economy. Together, we can create a future that benefits all through innovation and technological collaboration."

"As global demand for semiconductors continues to arise, navigating the challenges and seizing the opportunities ahead necessitates a unified effort across the entire supply chain," said TSMC Senior Vice President and Deputy Co-COO, Dr. Cliff Hou. "We extend our sincere gratitude to all our partners for your hard work over the past year, which has supported TSMC's continued growth, especially in the timely expansion of advanced packaging technologies capacity. TSMC looks forward to continuing our collaboration as we move towards shared success."

During the event, TSMC Chairman & CEO Dr. C.C. Wei and Senior Vice President and Deputy Co-COO Dr. Cliff Hou presented the 2024 Excellent Performance Awards to commend suppliers with outstanding performance in the innovation, technology collaboration, global production support, green manufacturing, automation systems and fab construction management categories. TSMC thanked suppliers for delivering timely and high-quality professional services to drive continuous improvement of the supply chain and related industries.



The list of winners of the 2024 TSMC Excellent Performance Award is as follows (in alphabetical order):

- Applied Materials, Inc. - Excellent Technology Collaboration
- ASAHI KASEI CORPORATION - Excellent Technology Collaboration and Production Support in Advanced Packaging
- ASM International N.V. - Excellent Production Support
- ASML - Excellent Production Support
- Canon Inc. - Excellent Production Support in Advanced Packaging
- DACIN CONSTRUCTION CO.,LTD - Excellent Performance in New Fab Construction
- DISCO Corporation - Excellent Production Support in Advanced Packaging
- HSINGMIEN INDUSTRY CO.,LTD. - Excellent Production Support
- JX Advanced Metals Corporation - Excellent Technology Collaboration and Production Support
- KLA Corporation - Excellent Technology Collaboration and Production Support
- Lam Research Corporation - Excellent Contribution in Green Manufacturing and Excellent Technology Collaboration and Production Support
- LCY Group - Excellent Contribution in Green Manufacturing
- MURATA MACHINERY, LTD. - Excellent Performance in Fab Automation
- NAMICS CORPORATION - Excellent Technology Collaboration and Production Support in Advanced Packaging
- NuFlare Technology, Inc. - Distinguished Mask Writer Collaboration
- Organo Technology Co., Ltd. - Excellent Performance in New Fab Construction
- Scientech Corporation - Excellent Production Support in Advanced Packaging
- SCREEN Semiconductor Solutions Co., Ltd. - Excellent Contribution in Green Manufacturing and Excellent Production Support
- SHIBAURA MECHATRONICS CORPORATION - Excellent Production Support in Advanced Packaging
- Shin-Etsu Chemical Co., Ltd. - Excellent Production Support
- SUMCO CORPORATION - Excellent Production Support
- Technoprobe S.p.A - Excellent Production Support
- TOKYO ELECTRON LIMITED - Excellent Technology Collaboration and Production Support
- TOKYO OHKA KOGYO CO., LTD. - Novel Technology Collaboration
- TOPCO QUARTZ PRODUCTS CO., LTD. - Excellent Production Support
- TUNG KANG STEEL STRUCTURE CORP - Excellent Performance in New Fab Construction
- United Integrated Services Co., Ltd. - Excellent Performance in New Fab Construction



About TSMC

TSMC pioneered the pure-play foundry business model when it was founded in 1987 and has been the world's leading dedicated semiconductor foundry ever since. The Company supports a thriving ecosystem of global customers and partners with the industry's leading process technologies and portfolio of design enablement solutions to unleash innovation for the global semiconductor industry. With global operations spanning Asia, Europe, and North America, TSMC serves as a committed corporate citizen around the world.

TSMC deployed 288 distinct process technologies, and manufactured 11,895 products for 528 customers in 2023 by providing the broadest range of advanced, specialty and advanced packaging technology services. The Company is headquartered in Hsinchu, Taiwan. For more information, please visit <https://www.tsmc.com>.

#

TSMC Spokesperson:

Wendell Huang
Senior Vice President and CFO
Tel: 886-3-505-5901

Media Contacts:

Nina Kao
Head of Public Relations
Tel: 886-3-563-6688 ext.7125036
Mobile: 886-988-239-163
E-Mail: nina_kao@tsmc.com

Doris Lien
Public Relations
Tel: 03-5636688 ext.7125033
Mobile: 886-963-854-707
E-Mail: pylien@tsmc.com